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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Wolfgang Klein	08/26/2009
Hans Taddiken	08/26/2009
Winfried Bakalski	09/03/2009

RECEIVING PARTY DATA

Name:	Infineon Technologies AG	
Street Address:	Am Campeon 1-12	
City:	Neubiberg	
State/Country:	GERMANY	
Postal Code:	85579	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12533919

CORRESPONDENCE DATA

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Email: clark@slater-matsil.com
Correspondent Name: Slater & Matsil, L.L.P.
Address Line 1: 17950 Preston Rd.

Address Line 2: Suite 1000

Address Line 4: Dallas, TEXAS 75252

ATTORNEY DOCKET NUMBER:	INF 2009 P 50166 US
NAME OF SUBMITTER:	Kimberley Clark

Total Attachments: 4

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PATENT REEL: 023278 FRAME: 0994 12533919

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> PATENT REEL: 023278 FRAME: 0995

Autorney Docket No. INF 2009 P 50166 US

ASSIGNMENT

For good and valuable consideration, I, Wolfgang Klein, residing at Am Wall 15, 85604 Zorneding, Germany, a citizen of Germany; Hans Taddiken, residing at Sandgrubenweg 144, 81737 Muenchen, Germany, a citizen of Germany, Winfried Bakalski, residing at Raintaler Str.

34, 81539 Muenchen, Germany, a citizen of Germany;

hereby sell, assign, and transfer to Infineon Technologies AG, a corporation organized and

existing under the laws of Germany, having its principal place of business at Am Campeon 1-12,

85579 Neubiberg, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title

and interest in and for the United States and all foreign countries, in and to any and all

improvements which are disclosed in the application for United States Letters Patent, which has

been executed by the undersigned concurrently herewithin, and is entitled:

Electrostatic Discharge Protection Element and Electrostatic Discharge Protection Chip

and Method of Producing the Same

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all

other applications for Letters Patent which have been or shall be filed in the United States and all

foreign countries on any of said improvements; and in and to all original and reissued patents which

have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its

own name, and that, when requested, without charge to but at the expense of said Assignee, their

successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this

agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and

all other patent applications on any and all said improvements; execute all rightful oaths,

assignments, powers of attorney and other papers, communicate to said Assignee, its successors,

assigns, and representatives, all facts known to the undersigned relating to said improvements and

the history thereof; and generally do everything possible which said Assignee, its successors,

Page 1 of 2

REEL: 023278 FRAME: 0996

assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:	8/26/203	Wolfgang Klein
Date:	8/26/2009	Hans Taddiken
Date:		Winfried Bakalski

Attorney Docket No. (NF 2009 P 50166 US

ASSIGNMENT

For good and valuable consideration, I, Wolfgang Klein, residing at Am Wall 15, 85604 Zorneding, Germany, a citizen of Germany; Hans Taddiken, residing at Sandgrubenweg 144, 81737 Muenchen, Germany, a citizen of Germany; Winfried Bakalski, residing at Raintaler Str. 34, 81539 Muenchen, Germany, a citizen of Germany;

hereby sell, assign, and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at Am Campeon 1-12, 85579 Neubiberg, Germany;

hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewithin, and is entitled:

Electrostatic Discharge Protection Element and Electrostatic Discharge Protection Chip and Method of Producing the Same

and in and to said application and all divisional, continuing substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements in its own name, and that, when requested, without charge to but at the expense of said Assignee, their successors, assigns, and legal representatives to carry out in good faith the intent and purpose of this agreement, the undersigned will execute all divisional, continuing substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors,

Page 1 of 1

assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:	•	Wolfgang Klein
Date:		Hans Taddiken
Date:	09/03/09	Winfried Bakalski

Page 2 of 2

PATENT REEL: 023278 FRAME: 0999